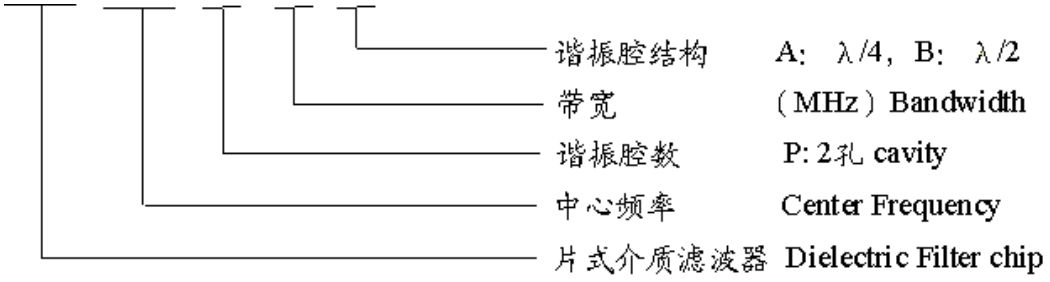
● 概述 INTRODUTION

微波介质滤波器系列产品设计用于移动和无绳电话机中，具有低的插入损耗，高的衰减和片式设计，能减少复杂的调校工作，可以简化电路设计.

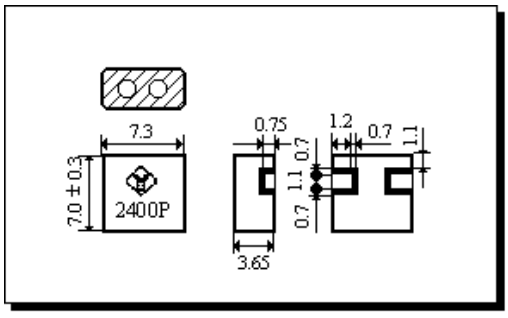
Microwave Dielectric filter series are designed to be used in mobile & cordless phones with low insertion loss and high attenuation as well as chip design , which can simplify your complex tunning and circuit design .

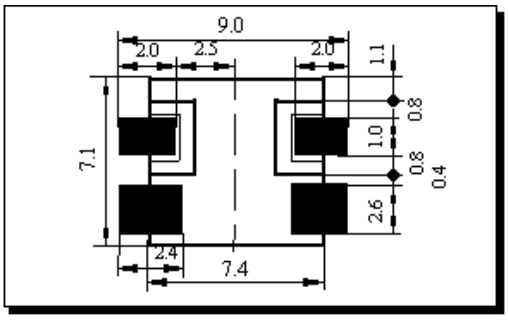
● 型号 Part Number

DFC 2400 P 06 A



● 外型尺寸 Dimension Unit mm





● 结构及材料 Structure and Material

表 1

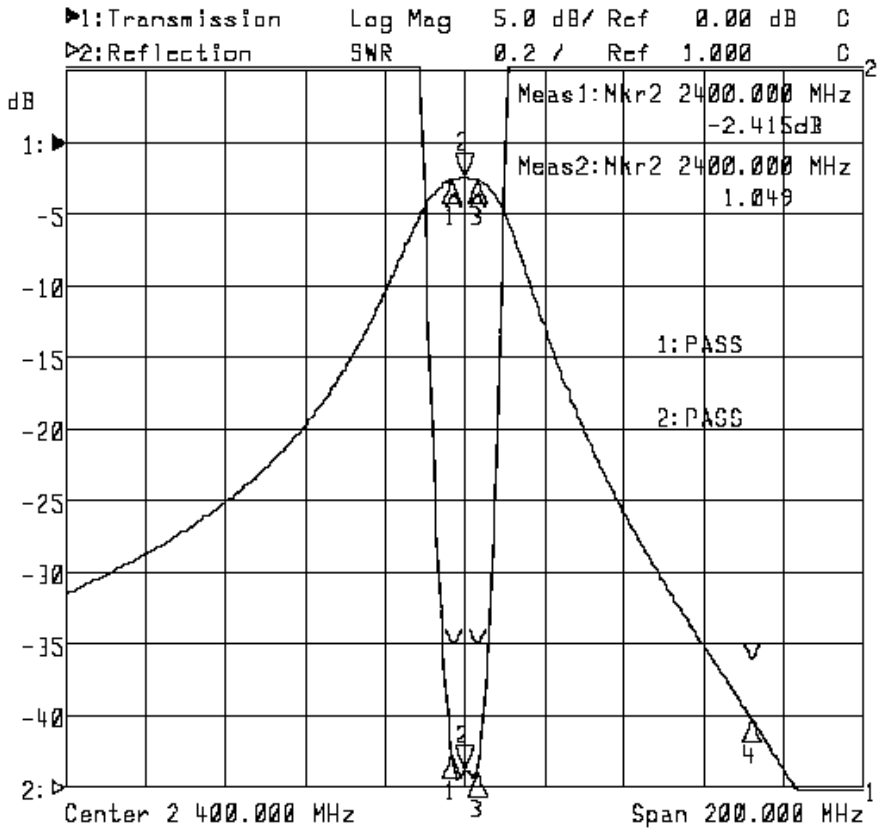
No.	Part Name	名称	Structure and material	结构及材料
4.1	Resonator	谐振体	Dielectric material	介质材料
4.2	Number of pole	电极数	2 pole	2 个电极
4.3	In/output Terminals	输入输出端子	Ag Plated	镀银
4.4	Ground Base	接地面	Ag Plated	镀银

● 电气性能　Electrical Characteristics

表 2

No.	Item（项目）	Specifications（特性）	Post Environmental Tolerance（环境试验后允许附加误差）
5.1	Center frequency 中心频率(fo)	2400.00 MHz	±1.5MHz
5.2	Insertion loss 插入损耗	≤3.5 dB	±0.5 dB
5.3	Band width 通带宽度	fo±3.0 MHz	±0.5 MHz
5.4	Ripple (in BW) 通带波动	0.5 dB Max.	±0.5 dB
5.5	V.S.W.R (in BW) 驻波比	2.0 Max.	±0.5
5.6	Attenuation (Absolute value) 阻带衰耗（绝对值）	35dBmin(fo+72.0MHz)	±2 dB
5.7	Permissible Input power (Max) 允许最大输入功率	1 Watt	——
5.8	In/output impedance 输入/输出阻抗	50Ω	——

● 特性曲线　Characteristic curve



- 环境试验　Environmental specifications

经环境试验后允许比起始读数偏差见表 2

Post Environmental Tolerance (Refer to the table 2)

基准条件: 温度范围　Temperature range　25–/+3 ℃

相对湿度范围　Relative Humidity range　55~75%RH

工作温度　Operating Temperature range　-10 ℃ ~+70 ℃

贮藏温度　Storage Temperature range　-25 ℃ ~+85 ℃

- 耐湿热特性　Moisture Proof

在温度为 40–/+2 ℃, 相对温度 90~95%的恒温湿箱中放置 96 小时, 在常温中恢复 1~2 小时后测试, 符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature 40–/+2 ℃ and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condlition.

- 耐振动　Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X , Y and Z directions.

- 耐跌落冲击　Drop Shock

在 30cm 高度处按 X,Y,Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after dropping onto the hard wooden board from the height of 30cm for 3 times each facet of the 3 dimensions of the device.

- 高温特性 High Temperature Endurance

在温度为 80–/+5 ℃ 的恒温箱中放置 24–/+2 小时, 在常温中恢复

1~2 小时后测试　符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to temperature 80–/+5℃ for 24–/+2 hours and 1~2 hours recovery time under normal temperature.

- 低温特性　Low Temperature Endurance

在温度为-25℃–/+3℃低温箱中放置 24–/+2 小时后恢复 1~2 小时测试符合表 5.1~5.6 规定.

The device should also satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature -25℃–/+3℃ for 24–/+2 hours and to 2 hours recovery time under normal temperature.

- 温度循环　　Temperature Cycle Test

在-25℃温度中保持 30 分钟, 再在+85℃温度中保持 30 分钟, 共循环 5 次后在常温中恢复 1~2 小时后测试符合表 5.1~5.6 规定.

The device should also satisfy the electrical characteractics specified in paragraph 5.1~5.6 after exposed to the low temperature -25℃ and high temperature +85℃ for 30–/+2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

- 耐焊接热　Solder Heat Proof

能承受经 120~150℃的温度预热 60 秒后, 在 260℃ +10℃的焊锡浸 10–/+0.5 秒.

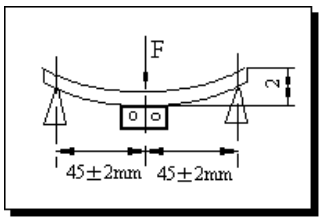
The device should be satisfied after preheating at 120℃ ~150℃ for 60 seconds and dipping in soldering Sn at 260℃ +10℃ for 10–/+0.5 seconds.

- 结合力试验　Tensile Strength of Terminal

在产品电极端子上或表面上应能承受 1kg 垂直拉力 10–/+1 秒.

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10–/+1 seconds.

- 耐弯曲试验 Bending Resist Test



将产品按图焊在 1.6–/+0.2mm 的 PCB 板中间，由箭头方向施力：1mm/S，弯曲距离：2mm，保持 5–/+1S，产品金属层无脱落.

Weld the product to the center part of the PCB with the thickness 1.6–/+0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of : 1mm/S , and hold for 5–/+1S at the position of 2mm bending distance , so far , any peeling off of the product metal coating should not be detected .

- 回流焊温度 Reflow Soldering Standard Condision